

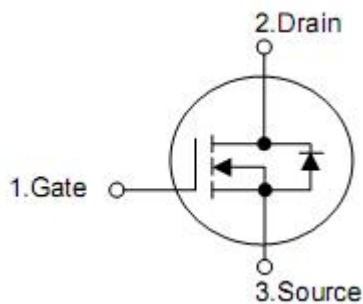
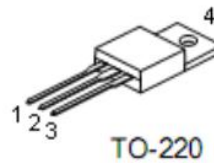
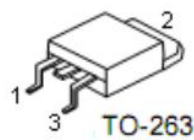
1. Features

- $R_{DS(ON),typ.}=3.5m\Omega @V_{GS}=10V$
- Uses CRM(CQ) advanced Trench MOS technology
- Excellent $Q_{gx}R_{DS(on)}$ product(FOM)
- Extremely low on-resistance $R_{DS(on)}$

2. Application

- Motor control and drive
- Battery management
- UPS

3. Pin configuration



Pin	Function
1	Gate
2,4	Drain
3	Source

4. Ordering Information

Part Number	Package	Brand
KNP2804B	TO-220	KIA
KNB2804B	TO-263	KIA

5. Absolute maximum ratings

TC=25 °C unless otherwise specified

Parameter		Symbol	Ratings	Unit
Drain-to-Source Voltage		V_{DSS}	40	V
Gate-to-Source Voltage		V_{GSS}	±20	
Continuous Drain Current	$T_C=25\text{ °C}$	I_D	150	A
	$T_C=100\text{ °C}$		90	
Pulsed Drain Current	$T_C=25\text{ °C}(t_p \text{ limited by } T_{jmax})$	I_{DM}	600	
Avalanche Energy ¹		E_{AS}	625	mJ
Maximum power Dissipation	$T_C=25\text{ °C}$	P_D	178	W
			1.42	W/°C
Junction & Storage Temperature Range		$T_J \& T_{STG}$	-55 to 150	°C

6. Thermal characteristics

Parameter	Symbol	Ratings	Units
Thermal resistance, Junction-case	$R_{\theta JC}$	0.7	°C/W
Thermal resistance, junction-ambient	$R_{\theta JA}$	62.5	°C/W

7. Electrical characteristics

(T_J=25°C, unless otherwise notes)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V
Gate leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Drain-source on-resistance ³	R _{DS(on)}	V _{GS} =10V, I _D =30A	-	3.5	4.5	mΩ
Dynamic characteristics						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V Frequency=1MHz	-	2.0	-	Ω
Input capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1MHz	-	5600	-	pF
Output capacitance	C _{oss}		-	545	-	pF
Reverse transfer capacitance	C _{rss}		-	400	-	pF
Turn-on delay time	t _{d(on)}		V _{DS} =20V, I _D =150A, V _{GS} =10V, R _G =24Ω	-	51	-
Rise time	t _r	-		130	-	ns
Turn-off delay time	t _{d(off)}	-		245	-	ns
Fall time	t _f	-		180	-	ns
Gate Charge Characteristics						
Total gate charge	Q _g	V _{DS} =32V, I _D =80A, V _{GS} =10V	-	110	-	nC
Gate-source charge	Q _{gs}		-	29	-	nC
Gate-drain charge	Q _{gd}		-	31	-	nC
Diode characteristics						
Diode forward voltage	V _{SD}	V _{GS} =0V, I _{SD} =30A	-	0.83	1.3	V
Drain Continuous Forward current	I _S		-	-	150	A
Reverse recovery time	t _{rr}	I _F =40A, V _{GS} =0V di/dt=100A/μs	-	28.5	-	ns
Reverse recovery charge	Q _{rr}		-	0.02	-	uC

Note:

[1] L=0.5mH, VDD=40V, R_G=25Ω.

[2] Repetitive rating; pulse width limited by maximum junction temperature.

[3] Pulse width ≤ 380μs; duty cycle ≤ 2%.

8. Typical Characteristics

图 1. 输出特性

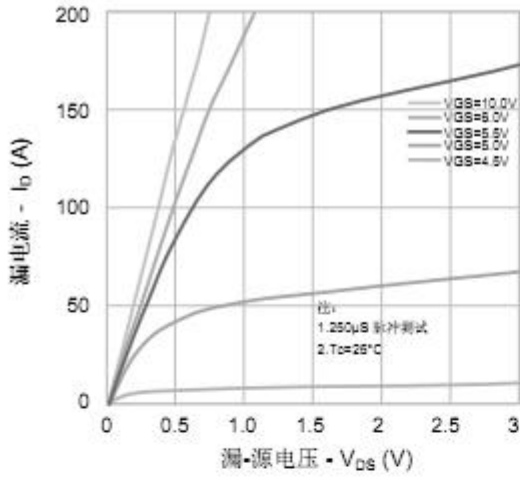


图 2. 传输特性

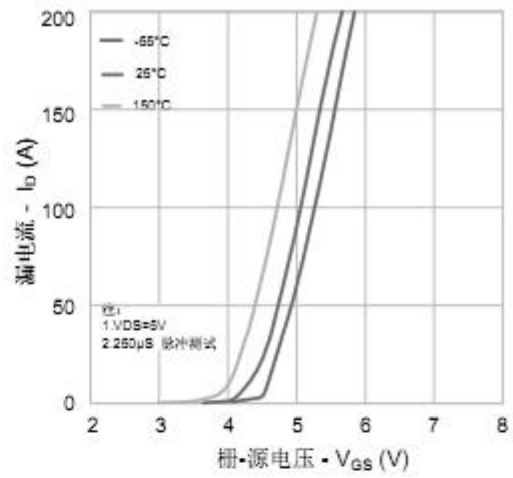


图 3. 导通电阻 vs. 漏电流

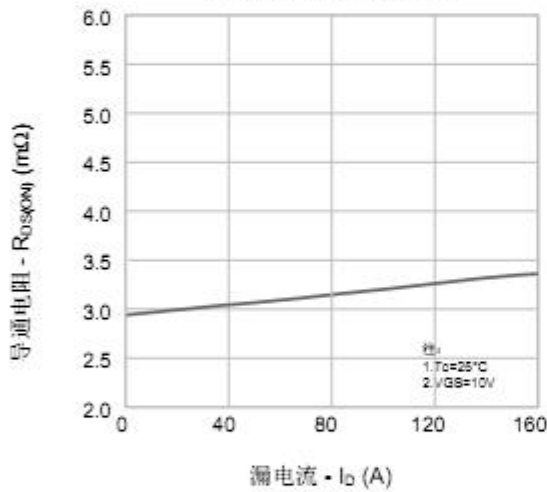


图 4. 体二极管正向压降 vs. 源电流和温度

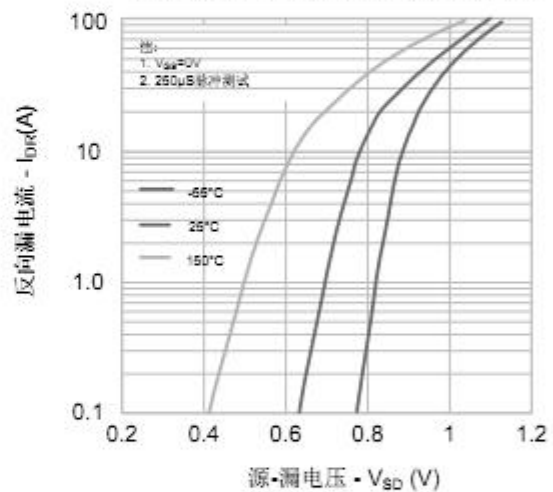


图 5. 电容特性

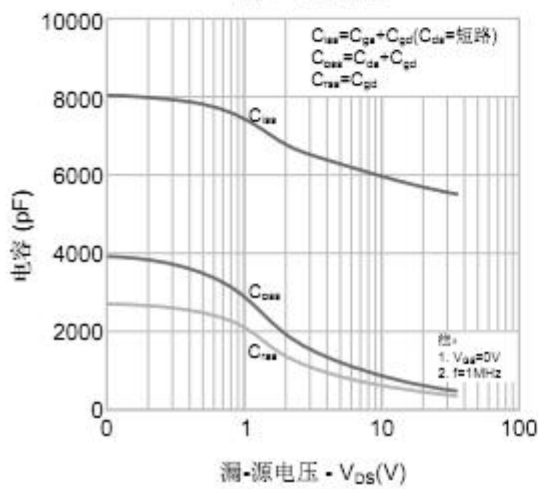


图 6. 栅极电荷特性

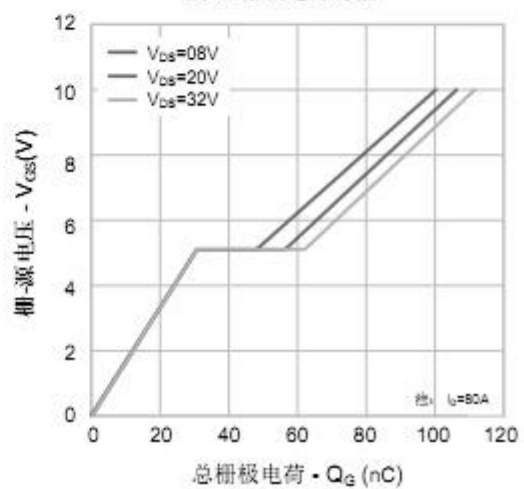


图 7. 击穿电压 vs. 温度特性

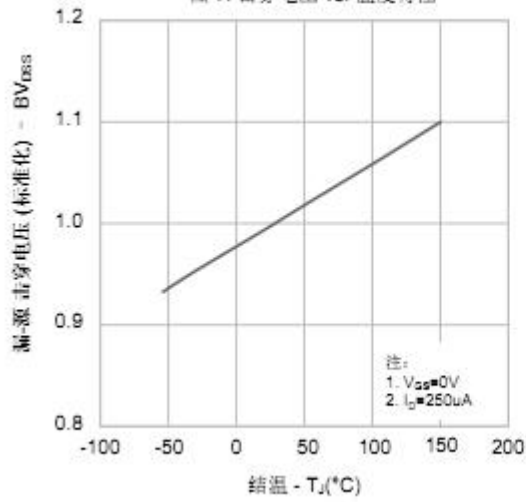


图 8. 导通电阻 vs. 温度特性

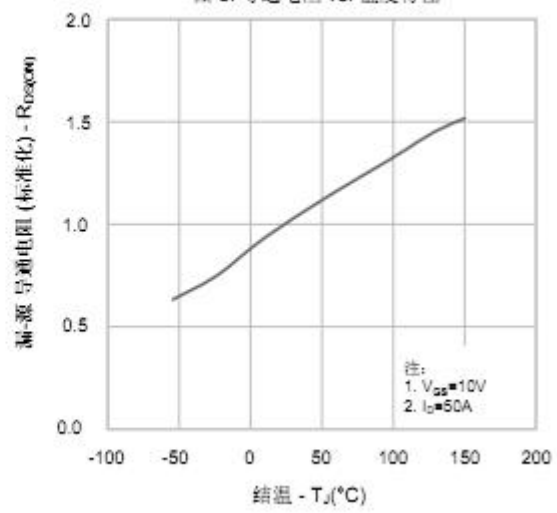


图 9- . 最大安全工作区域

